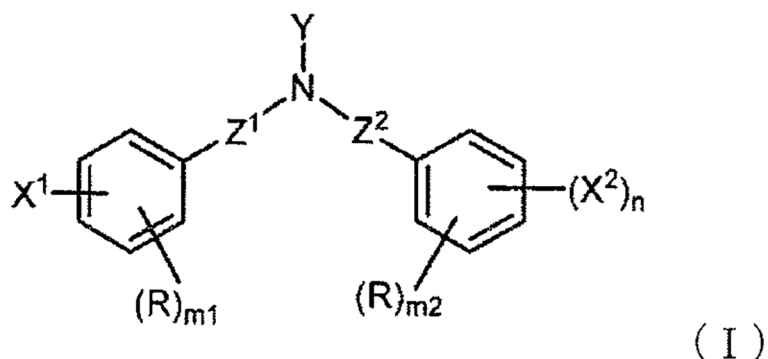


**NOVEL POLYMER, RESIN COMPOSITION INCLUDING SAME, AND  
MOLDED BODY THEREOF**

**ABSTRACT**

An object of the present invention is to provide a polymer that has excellent heat resistance and dielectric properties and can be dissolved in an organic solvent at a high concentration, a resin composition containing the same, and a molded body thereof. The polymer of the present invention has a repeating unit derived from a polymerizable compound of the following formula (I) (In the formula,  $X^1$  and  $X^2$  each independently represent a C3 to C6 branched alkyl group, a C3 to C6 cyclic alkyl group, a C3 to C6 branched alkoxy group, or a C3 to C6 cyclic alkoxy group,  $n$  represents 0 or 1,  $Z^1$  and  $Z^2$  each independently represent a single bond or a C1 to C3 alkylene group, each  $R$  independently represents an organic group or a halogeno group,  $m_1$  and  $m_2$  each independently represent any integer of 0 to 4, and  $Y$  represents a polymerizable functional group).



[No Available Figure]